PRESS RELEASE

AIXTRON
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AIXTRON receives CS High-Volume Manufacturing Award

Business magazine honors innovative GaN-on-Si production system AIX G5+ C with renowned industry award

Herzogenrath/Germany, March 04, 2016 – AIXTRON SE (FSE: AIXA; NASDAQ: AIXG), a worldwide leading provider of deposition equipment to the semiconductor industry, has received the CS High-Volume Manufacturing Award 2016 for its new fully automated MOCVD system AIX G5+ C at this year's CS Industry Awards. The peer decided prize for the international compound semiconductor industry recognizes key areas of innovation surrounding the chip manufacturing process from research to completed device, focusing on the people, processes and products that drive the industry forward.

"Two great opportunities to slash manufacturing costs are to scale to larger wafers and switch growth to silicon substrates. With AIXTRON's latest tool, both options are readily available", the judges from Compound Semiconductor commented the decision.

Dr. Frank Wischmeyer, Vice President Marketing & Business Development Power Electronics at AIXTRON, who accepted the award during the CS International conference in Brussels, said: "The AIX G5+ C is the first complete MOCVD system solution addressing the epitaxy production needs of the GaN-on-Si LED and power device industry. By combining two key innovations into one new product, AIXTRON is enabling a continuous LED or HEMT MOCVD process flow without operator interaction with the high capacity 150 mm and 200 mm batch system architecture. It is the first time that an industry standard solution of operation of MOCVD tools in Si CMOS lines is created by adding wafer level automation with a wafer-cassette-to-cassette handler to the MOCVD batch technology."

The AIX G5+ C simplifies the handling of silicon wafers and processing in a fab environment and warrants production at highest yields. AIXTRON's proprietary in-situ chamber cleaning process enables full control of the chamber conditions without the need for external parts cleaning and without the need for reconditioning these parts in the MOCVD reactor after cleaning. This cleaning process runs fully automatically and eliminates any manual or automated removal of hardware components from the chamber for ex-situ clean or conditioning.

The AIX G5+ C system was successfully qualified for high-volume manufacturing by the GaN LED and power HEMT industry demonstrating significant gain in wafer throughput and product yield.

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About AIXTRON
AIXTRON SE is a leading provider of deposition equipment to the semiconductor industry. The Company was founded in 1983 and is headquartered in Herzogenrath (near Aachen), Germany, with subsidiaries and sales offices in Asia, United States and in Europe. AIXTRON's technology solutions are used by a diverse range of customers worldwide to build advanced components for electronic and opto-electronic applications based on compound, silicon, or organic semiconductor materials. Such components are used in a broad range of innovative applications, technologies and industries. These include LED applications, display technologies, data storage, data transmission, energy management and conversion, communication, signaling and lighting as well as a range of other leading-edge technologies.

For further information on AIXTRON (FSE: AIXA, ISIN DE000A0WMPJ6; NASDAQ: AIXG, ISIN US0096061041) please visit our website at: www.aixtron.com.

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